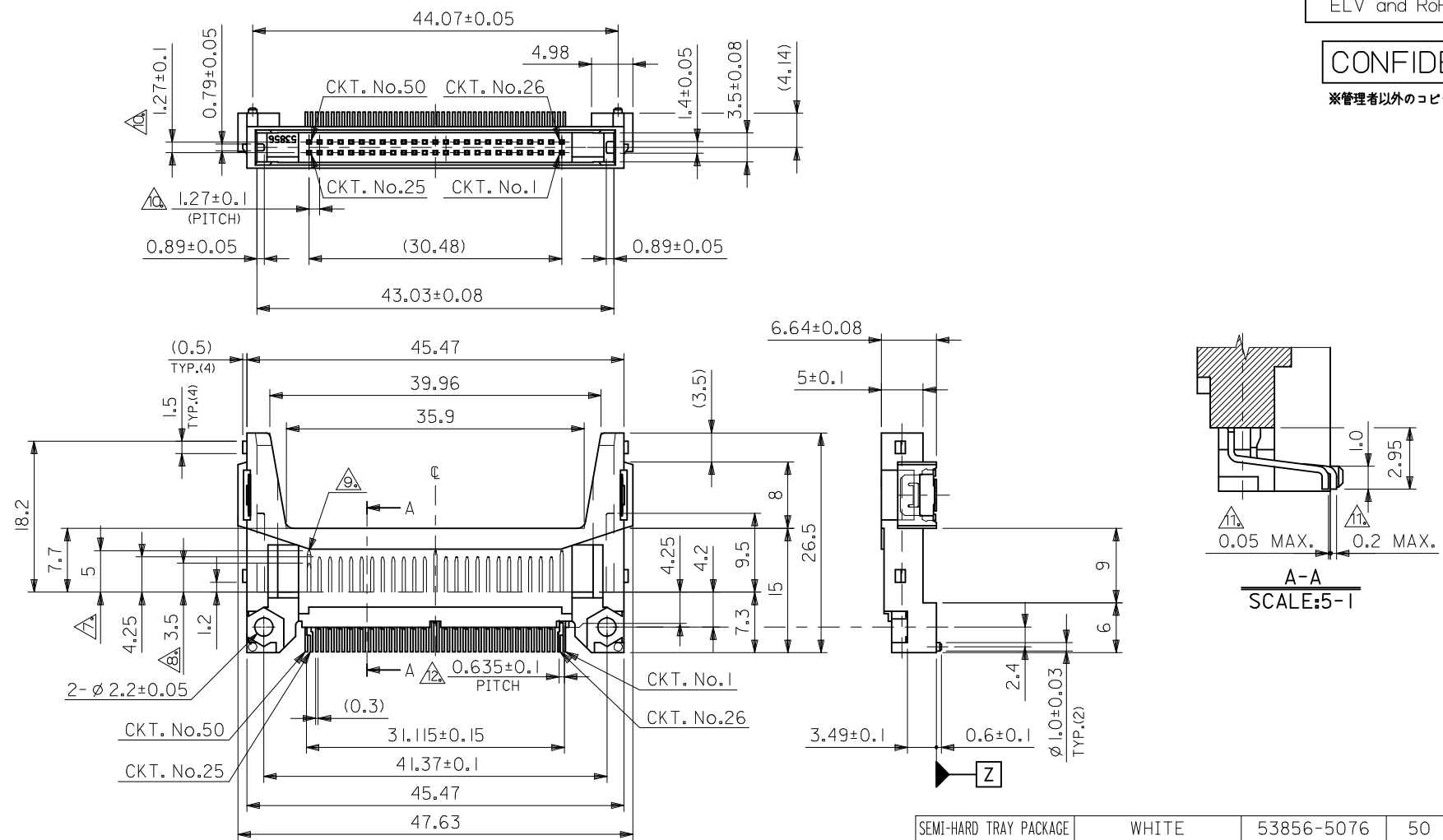


ELV and RoHS Compliant

**CONFIDENTIAL**

※管理者以外のコピー及び配布を禁ずる



SEMI-HARD TRAY PACKAGE	WHITE	53856-5076	50	53856-507*
SOFT TRAY PACKAGE	<del>BLACK</del>	<del>53856-5071</del>	<del>50</del>	
	WHITE	53856-5070	50	
PACKING TRAY FORM	HOUSING COLOR	MATERIAL No.	No. OF CKT.	MODEL No.

<b>REVISED</b> EC NO: J2015-1214 DRW:RWATANABE01 2015/03/11 CHK:D-AMI/ZUMURA 2015/03/17 APPR:MYAGI 2015/03/23	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS	
	0.25 UNDER	UNDER	±0.03	MM ONLY		---	METRIC	
	0.25 OVER	0.5 UNDER	±0.05	DRAWN BY		DATE	THIRD ANGLE PROJECTION	
	0.5 OVER	1.0 UNDER	±0.1	M. NABEI		'04/03/16	CF CARD CONN. HEADER ASS'Y -LEAD FREE-	
	1.0 OVER	10 UNDER	±0.2	CHECKED BY		DATE		
10 OVER	30 UNDER	±0.25	K. TOJO		'04/03/16			
30 OVER		±0.3	APPROVED BY		DATE	DOCUMENT NO.		
ANGULAR	±3 °		M. SASAO		'04/03/16	SD-53856-007		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO.		SEE CHART		SHEET NO.	
			SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		1 OF 2	

**CONFIDENTIAL**

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注) NOTES

- 材質  
MATERIAL  
ハウジング: ガラス入りLCP UL94V-0  
HOUSING: LCP G.F. UL94V-0  
ピン: リン青銅  
PIN: PHOSPHOR BRONZE  
ネール: リン青銅  
NAIL: PHOSPHOR BRONZE
- メッキ仕様  
PLATING  
PIN 接点部: ニッケル下地、パラジウムニッケル、金メッキ  
CONTACT AREA: PALLADIUM-NICKEL, GOLD OVER NICKEL  
半田付け部: 錫メッキ  
SOLDER TAIL AREA: TIN  
下地メッキ: ニッケルメッキ  
UNDERPLATING: NICKEL OVER ALL  
NAIL 錫メッキ  
TIN  
下地メッキ: ニッケルメッキ  
UNDERPLATING: NICKEL OVER ALL

- 推奨基板厚:  $t \geq 0.8$  MIN.  
RECOMMENDED P.C.B. THICKNESS:  $t \geq 0.8$  MIN.

- 適合カード厚  
RECOMMENDED CARD THICKNESS  
接続部:  $3.3 \pm 0.1$   
CONNECTING AREA:  $3.3 \pm 0.1$

- 適合カード幅:  $42.8 \pm 0.1$   
RECOMMENDED CARD WIDTH:  $42.8 \pm 0.1$

- ハウジング色:  
HOUSING COLOR:  
53856-5010: 白 (WHITE)  
53856-5010: 黒 (BLACK)

△寸 1,13,38,50  
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS  
1,13,38 AND 50.

△8 25,26  
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.

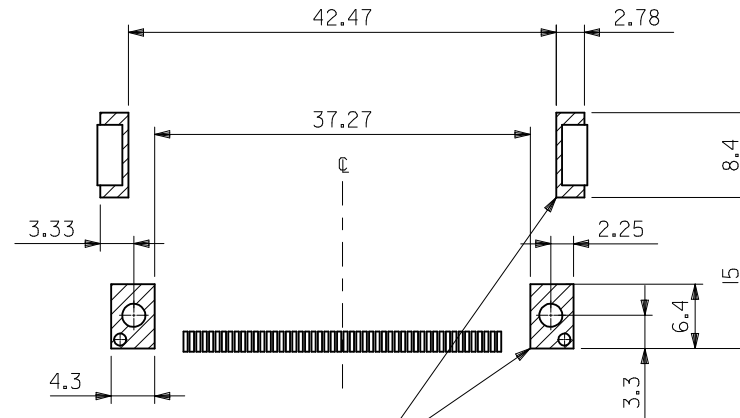
△9 ピンの倒れは、ピン根元を基準に全方向へ  $0.1$  MAX.とする。  
PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED  $0.1$   
WHEN MEASURED FROM PIN BASE.

△10 ピン根元に適用する。  
THIS DIMENSION TO BE MEASURED AT PIN BASE.

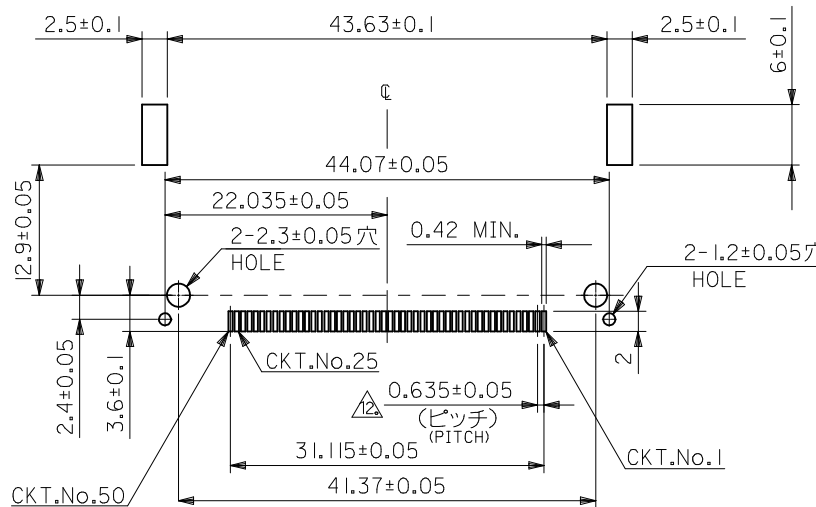
△11 ソルダータールは、Z面を基準とし上へ  $0.05$  下へ  $0.2$  の範囲にあり、  
且つソルダータールの平坦度は、 $0.15$  MAX.とし、テール先端にて測定する。  
SOLDERTAILS TO BE WITHIN  $0.05$  UPWARD AND  $0.2$  DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY  
OF SOLDERTAILS TO BE WITHIN  $0.15$ .  
MEASUREMENT POINT IS SOLDERTAILS TIP.

△12 公差非累積  
NON-CUMULATIVE

- 本製品は 53856-501\* の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53856-501\*.



部品実装不可エリア  
NO PARTS TO BE LOCATED IN THIS AREA.



基板推奨寸法  
RECOMMENDED P.C.B. LAYOUT

GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
0.25 OVER	0.5 UNDER	±0.05	M. NABEI	'04/03/16	CF CARD CONN. HEADER ASS'Y -LEAD FREE- <b>molex</b> DOCUMENT NO. SD-53856-007 SHEET NO. 2 OF 2		
0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE			
1.0 OVER	10 UNDER	±0.2	K. TOJO	'04/03/16			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE			
30 OVER		±0.3	M. SASAO	'04/03/16			
ANGULAR	±3 °		MATERIAL NO.		SEE SHEET 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			